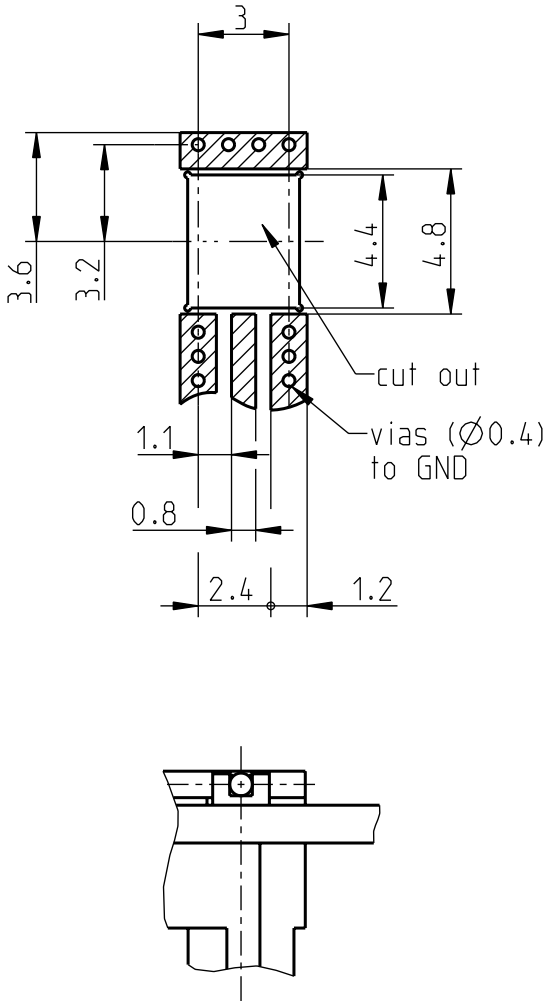
Formblatt: TCC_FB_05_PE_A4_Einzelteil
Pfad: I:\Creo-Config\Rahmen\
Datei: A4_EINZELTEIL-V2_1.FRM
Version: 2.1

Dimensions in mm

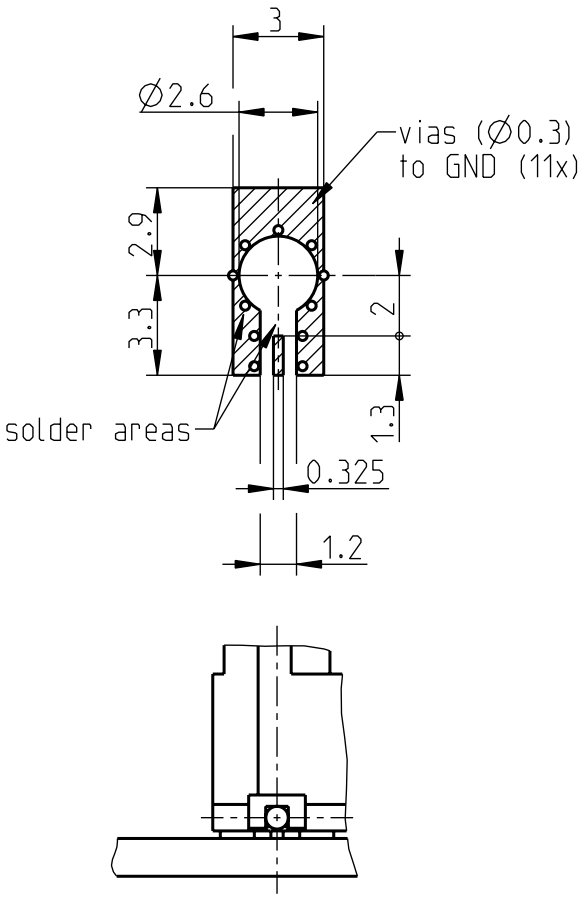
ISO-Projektion Methode 1

Leiterplatten-Layout
PCB layout
B 501

Feedthrough



SMD



A wide variety of transmission line topologies and pcb-parameters like permittivity, substrate thickness, and board-stack up are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.
Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.
In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Rosenberger	general tolerance: ISO 2768 mH; RN 006-01 dimensions <0,5 and symmetry	scale: 4:1 ( )	weight[g]: 8.384; surface[mm²]: 2151.0
		material:	
	date / name: drawn 11.09.2014 S_Andorfer; check. 17.09.2014 G_Schiele; appr. 17.09.2014 M_Moder; dimensioning incl. plating	title: Leiterplatten-Layout *PCB layout*	
a00 / 14-1309 / S_Andorfer / 17.09.2014 (rev. / change-no / name / date)	Size ISO 14405 (E) Tolerancing ISO 8015	drawing-no..: MB_501	sheet: 1 of: 1
		remarks: .	